 國家實驗研究院 台灣半導體研究中心 Taiwan Semiconductor Research Institute		DOCUMENT NO. : Q3-NL04	TITLE : 設備作業標準 (CF-E11 8吋後段金屬層與金屬層間引洞蝕刻機)		
ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 1 / 7 頁

一、The purpose: :

Define the production operation specifications of the 8-inch back-end metal layer and via etching machine to ensure the quality of equipment production operations. °

二、Scope of application: :


Applicable to 8-inch back-end metal layer and via etching machine. °

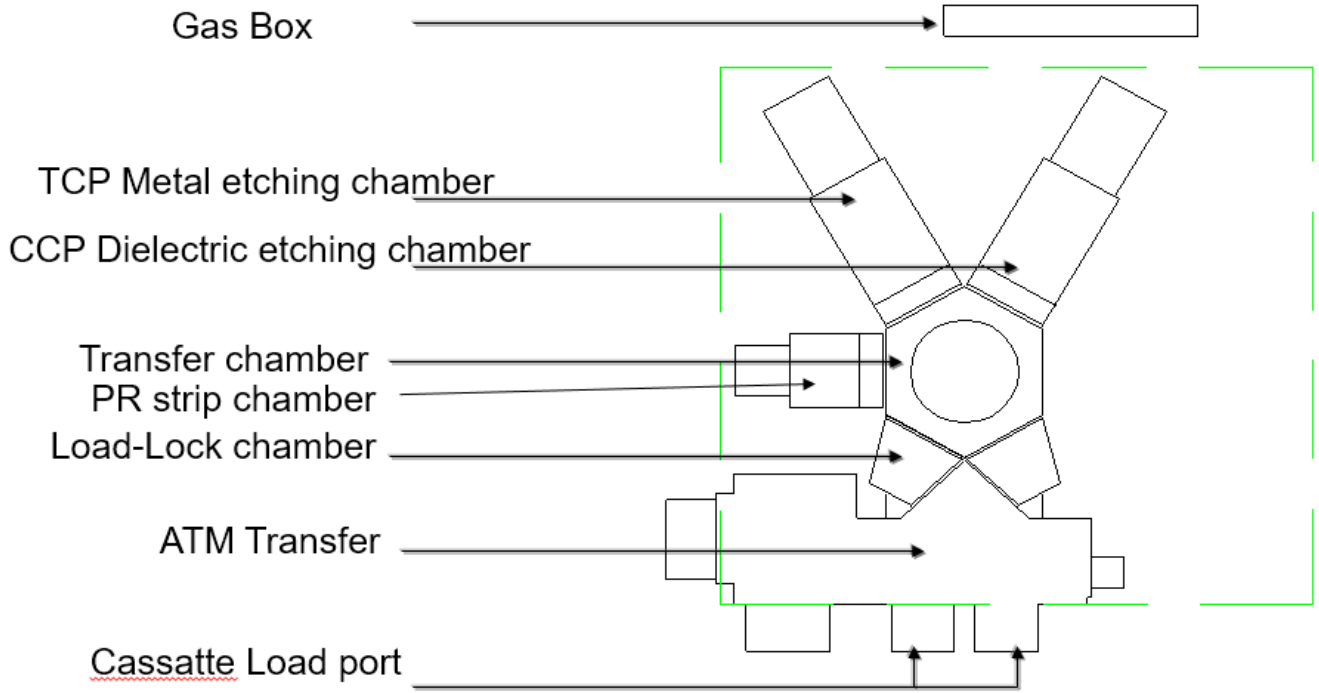
三、Responsibilities :


1. Organizational rights and responsibilities: Process personnel are responsible for formulating and revising specifications. °
2. The person in charge of the equipment is responsible for the abnormal handling of the machine and maintains the normal operation of production. °
3. Qualification of executive personnel: Etching department personnel who have passed the operation evaluation of the 8-inch rear metal layer and intermetallic hole etching machine. °

四、Related documents :

五、Introduction :

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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 2 / 7 頁




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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 3 / 7 頁

六、Operating procedures :

1. Check the condition of the machine, determine the current use of the machine (green: in use, red: in maintenance, yellow: in test), swipe the card to start the machine and user must be qualified personnel. °
2. Place the wafer in the cassette and select port1 or port2 to place it (as shown in Figure 1). After placing the wafer, confirm whether the position of the cassette and the wafer is correct.



Fig.1: Cassette & load port

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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 4 / 7 頁

3. At Operate mode (Fig.2)
 - (1) key in (Carrier ID and Lot ID)
 - (2) Chose recipe.
 - (3) Make sure wafer no.
 - (4) Press Start to process ◦

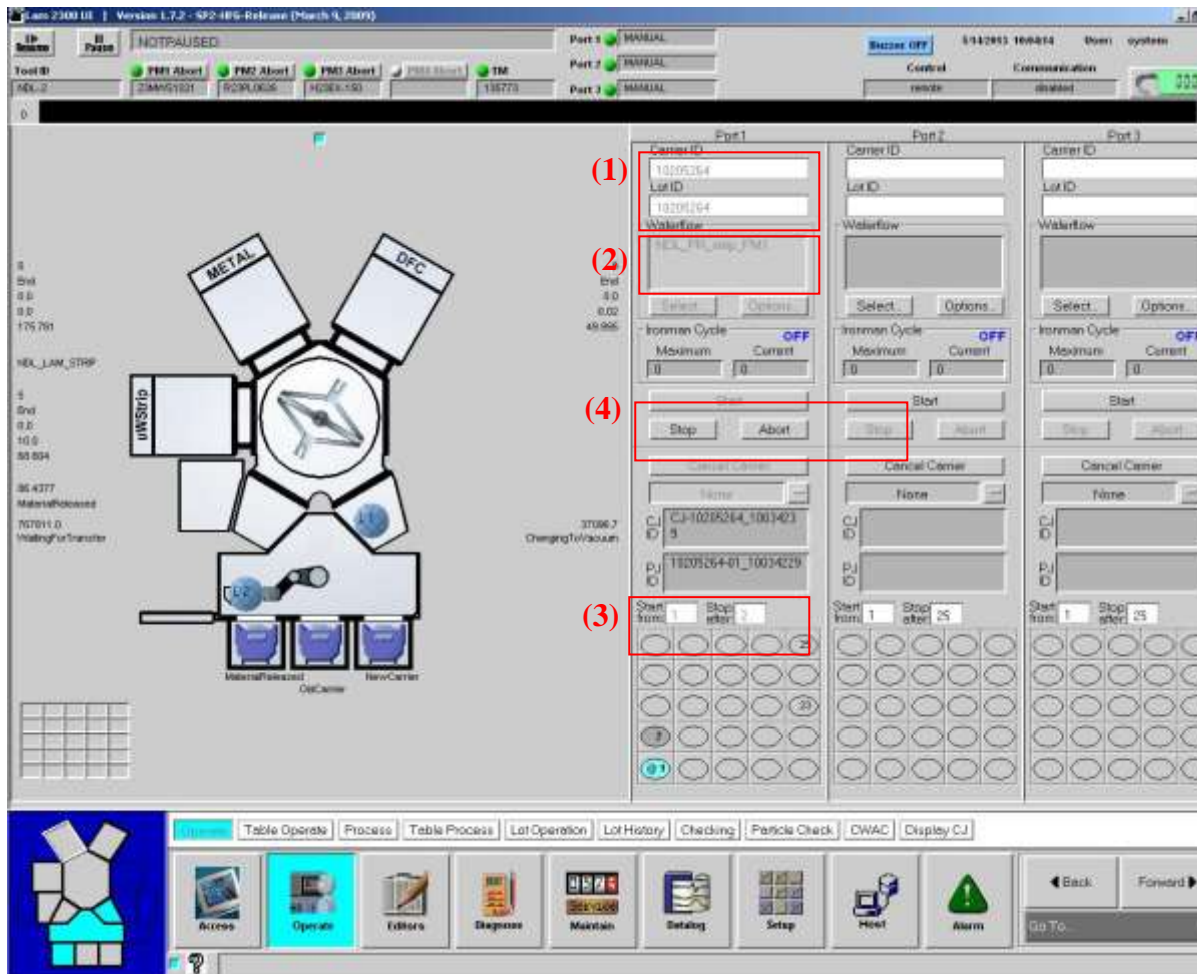



Fig.2: Operate mode page

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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 5 / 7 頁

4. From the color of wafer icon, show the wafer states. [Gray: not run、Green: Finished、Blue: in transfer、Yellow: Some error happened in process] (Fig. 3)。

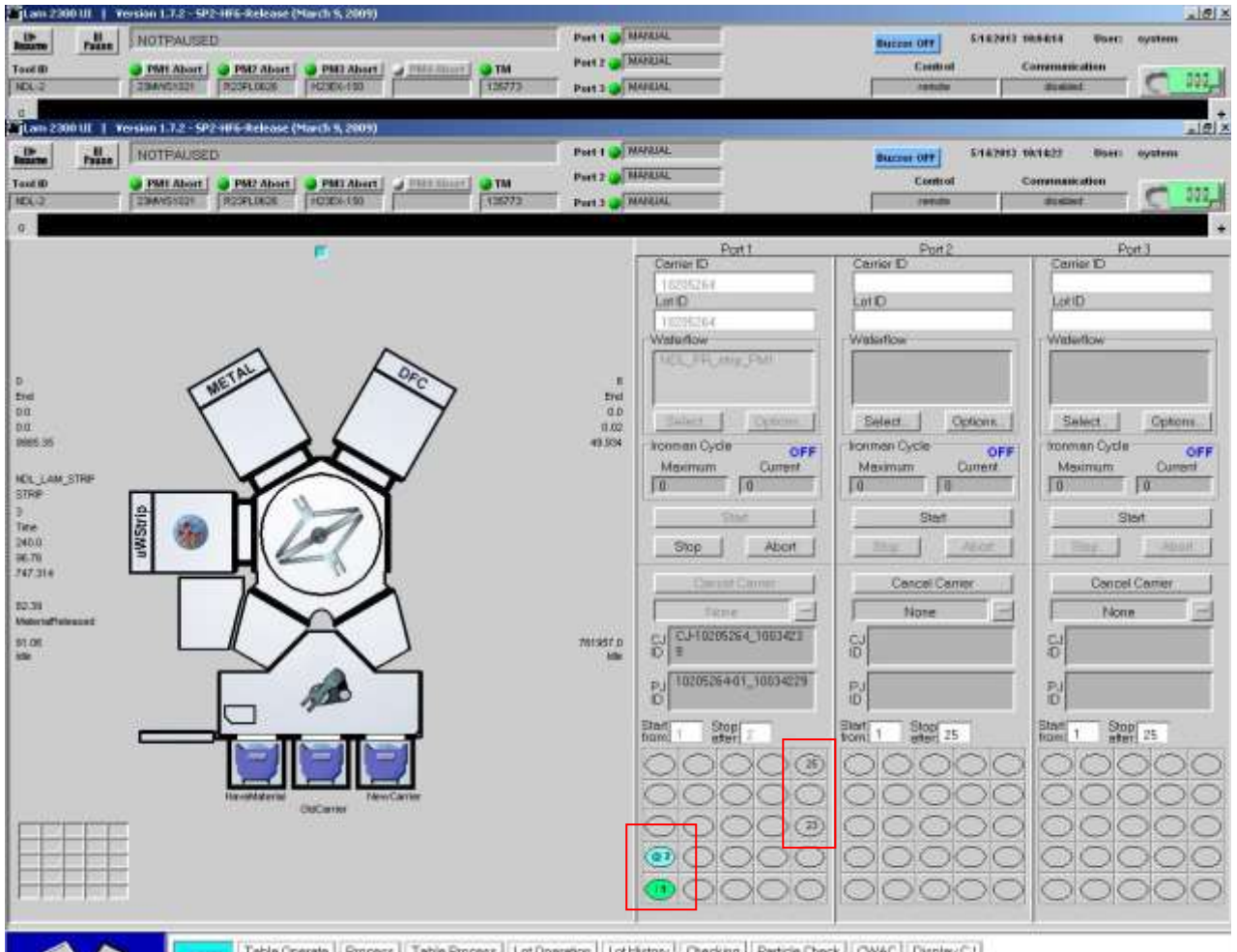



Fig.3: Wafer states

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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 6 / 7 頁

5. If chose wrong recipe, press " Abort 或 Stop" (fig.4).

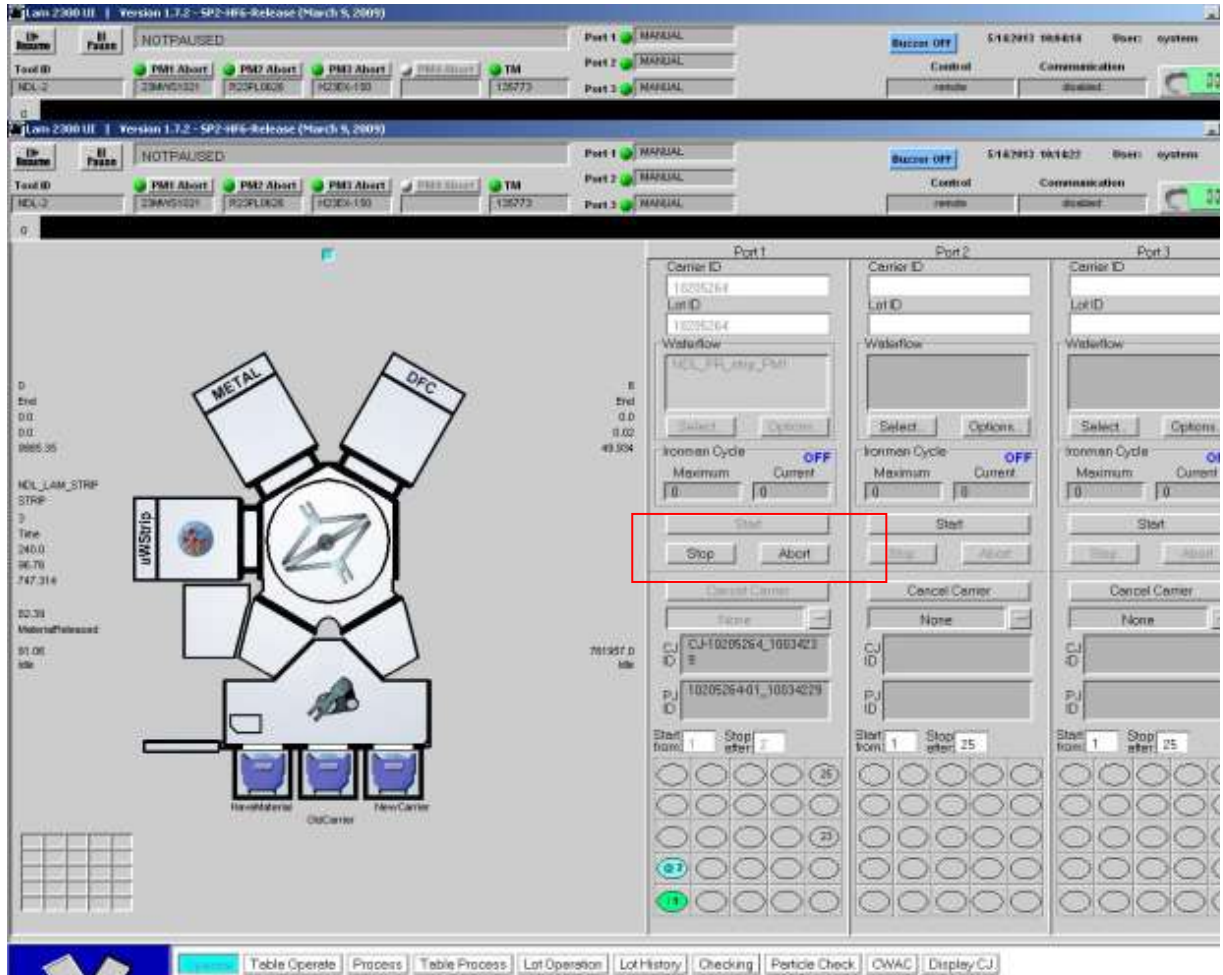



Fig.4: Abort and stop page

6. When process finish, can open port1 or port2 to take wafer.

7. When alarm (fig.5), note the error message and contact machine owner.

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ISSUE DATE	2023-05-11	REVISION	1.1	PAGE	第 7 / 7 頁

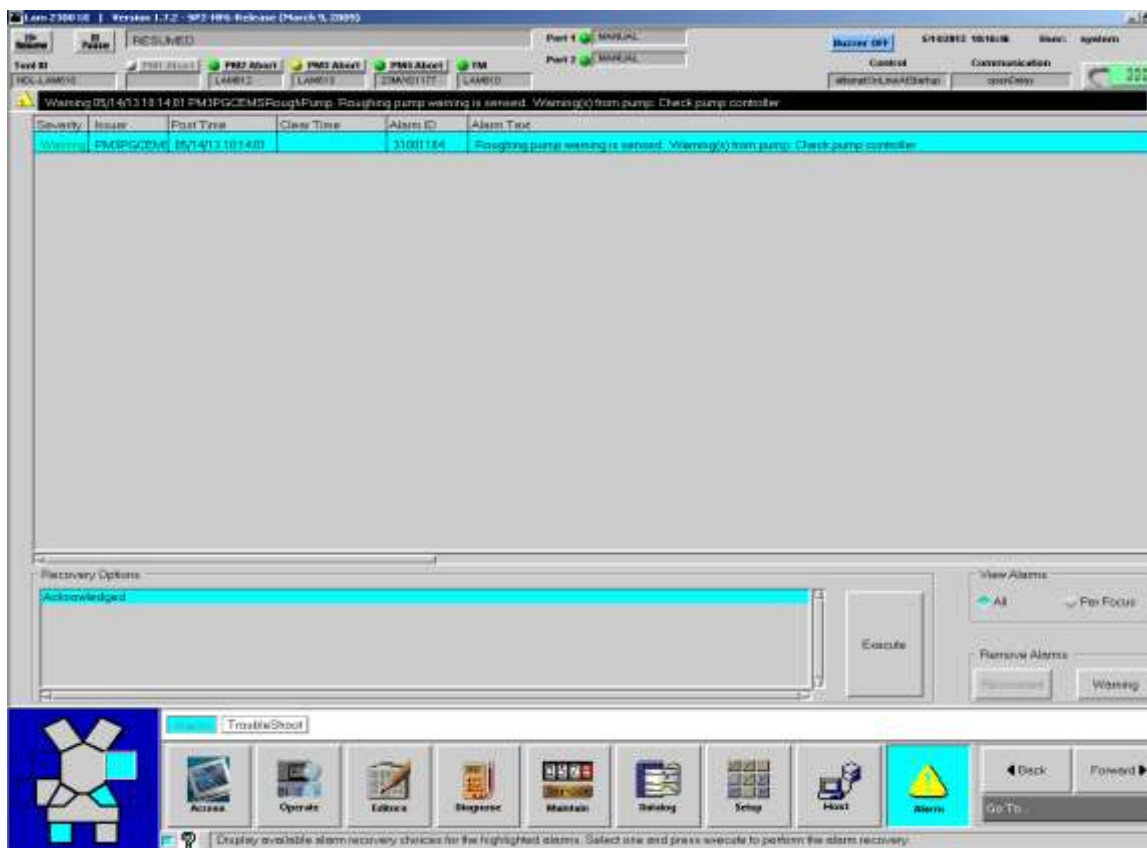


Fig.5: Alarm page

八、應用表單及附件：

1. 設備考核表 S4-NL01A
2. 設備點檢表 S4-NL01B
3. 設備使用記錄表 S4-NL01C
4. 異常及矯正預防處理單 S4-NL02A
5. 儀器設備管理卡 S4-NL04B.